

ESD Association Technical Report

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*For the Protection of Electrostatic
Discharge Susceptible Items*

Transmission Line Pulse (TLP)

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FOREWORD

Transmission Line Pulse (TLP) measurements have become an essential tool in the development and analysis of on chip ESD protection devices and networks. In an effort to improve the reproducibility between TLP measurements made at different locations and on different TLP systems, the Electrostatic Discharge Association (ESDA) Working Group 5.5, Device Testing (TLP), has been working toward a standard for TLP testing. The first stage in that process was completed with the issuance of a standard practice, ANSI/ESD SP5.5.1, Electrostatic Discharge Sensitivity Testing, Transmission Line Pulse (TLP), Component Level. During the development of the document a great deal of useful information was gathered that did not fit in a standard practice. This technical report is a compilation of the information gathered during the writing of ANSI/ESD SP5.5.1 and the information gathered in support of moving the standard practice toward redesignation as a standard test method.

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